WHAT IS CLAIMED IS:

1. An exposure method comprising the steps of:

- a) removing an unwanted deposited film from the surface of a photomask, a desired pattern having been formed in the photomask; and
- b) exposing a resist film to extreme ultraviolet radiation through the photomask, from which the deposited film has been removed, thereby transferring the desired pattern onto the resist film.
- 2. The method of Claim 1, wherein the step a) comprises removing the deposited film using oxygen plasma.
 - 3. An exposure method compaising the steps of:
- a) loading a substrate, on which a resist film has been formed, into a vacuum chamber;
- b) removing an unwanted deposited film from the surface of a photomask, having a desired pattern therein, inside the vacuum chamber by using oxygen plasma that has been generated in the chamber; and
- diation through the photomask, from which the deposited film has been removed, thereby transferring the desired pattern onto the resist film.

- 4. An exposure method comprising the steps of:
- a) removing an unwanted deposited film from the surface of a photomask, having a desired pattern therein inside a first vacuum chamber by using oxygen plasma that has been generated in the first vacuum chamber;
- b) loading a substrate, on which a resist film has been formed, into a second vacuum chamber;
- c) transporting the photomask, from which the deposited film has been removed, in line from inside the first vacuum chamber to inside the second vacuum chamber; and
- d) exposing the resist film to extreme ultraviolet radiation through the photomask inside the second vacuum chamber, thereby transferring the desired pattern onto the resist film.
 - 5. An exposure apparatus comprising:
 - a vacuum chamber;
- a substrate holder placed inside the vacuum chamber to hold a substrate thereon, a resist film having been formed on the surface of the substrate;
- an optical system disposed inside the vacuum chamber and used for exposing the resist film to extreme ultraviolet radiation through a photomask, in which a desired pattern has been formed, and thereby transferring the pattern from the photomask onto the resist film;

means for introducing oxygen gas into the vacuum chamber; and

means for generating a plasma out of the oxygen gas that has been introduced into the vacuum chamber.

- 6. An exposure apparatus comprising:
- a first vacuum chamber;

means for introducing oxygen gas into the first vacuum chamber;

means for generating a plasma out of the oxygen gas that has been introduced into the first vacuum chamber;

a second vacuum chamber;

a substrate holder placed inside the second vacuum chamber to hold a substrate thereon, a resist film having been formed on the surface of the substrate;

an optical system disposed inside the second vacuum chamber and used for exposing the resist film to extreme ultraviolet radiation through a photomask, in which a desired pattern has been formed, and thereby transferring the pattern from the photomask onto the resist film; and

means for transporting the photomask associated with the optical system in line from inside the first chamber to inside the second chamber or vice versa.

 $Add > b^2$